

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by

(Insert
ASSIGNEE'S
Name(s)
Address(es))

DAI NIPPON PRINTING CO., LTD.

of

1-1, Ichigaya-Kagacho 1-Chome, Shinjuku-Ku,

TOKYO 162-0062 JAPAN

(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

ETCHING SUBSTRATE MATERIAL, ETCHING PROCESS,

(Title of
Invention)

AND ARTICLE OBTAINED BY ETCHING

(*If the assignment
is being filed
after the
filing of the
application, this
section must be
completed)

for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:

* filed on _____, Serial No. _____

and all Letters Patent of the United States to be obtained therefor on said application or any continuation, division, renewal, substitute, reissue or reexamination thereof for the full term or terms for which the same may be granted.

The ASSIGNOR agrees to execute all papers necessary in connection with this application and any continuing, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.

The ASSIGNOR agrees to execute all papers necessary in connection with any interference or litigation which may be declared concerning this application or any continuation, division, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference or litigation.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Signatures)

Takayasu Komatsu
(SIGNATURE)

Takayasu KOMATSU November 5, 1998

(TYPE NAME)

(DATE)

Daisuke Hashimoto
(SIGNATURE)

Daisuke HASHIMOTO November 5, 1998

(TYPE NAME)

(DATE)

Akira Makita
(SIGNATURE)

Akira MAKITA November 5, 1998

(TYPE NAME)

(DATE)

Koji Fujiyama
(SIGNATURE)

Koji FUJIYAMA November 5, 1998

(TYPE NAME)

(DATE)

(SIGNATURE)

(TYPE NAME)

(DATE)

(SIGNATURE)

(TYPE NAME)

(DATE)

(SIGNATURE)

(TYPE NAME)

(DATE)

(SIGNATURE)

(TYPE NAME)

(DATE)

(SIGNATURE)

(TYPE NAME)

(DATE)

NO LEGALIZATION REQUIRED

DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that my residence, post office address and citizenship are as stated below next to my name: that I verily believe I am the original, first and sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of the subject matter claimed and for which a patent is sought in the application entitled:

ETCHING SUBSTRATE MATERIAL, ETCHING PROCESS,
AND ARTICLE OBTAINED BY ETCHING

which application is:

XX the attached application

(for original application)

_____ application Serial No. _____
filed _____, and amended on _____

(for declaration not accompanying application)

that I have reviewed and understand the contents of the specification of the above-identified application, including the claims, as amended by any amendment referred to above; that I acknowledge my duty to disclose information of which I am aware which is material to the patentability of this application under 37 C.F.R. 1.56, that I hereby claim foreign priority benefits under Title 35, United States Code §119, §172 or §365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified on said list any foreign application for patent or inventor's certificate on this invention having a filing date before that of the application on which priority is claimed:

Application Number	Country	Filing Date	Priority Claimed (yes or no)
9-312070	Japan	November 13, 1997	yes

I hereby claim the benefit of Title 35, United States Code §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in a listed prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge my duty to disclose any information material to the patentability of this application under 37 C.F.R. 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Application Serial No.	Filing Date	Status (patented, pending, abandoned)
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I hereby appoint John H. Mion, Reg. No. 18,879; Donald E. Zinn, Reg. No. 19,046; Thomas J. Macpeak, Reg. No. 19,292; Robert J. Seas, Jr., Reg. No. 21,092; Darryl Mexic, Reg. No. 23,063; Robert V. Sloan, Reg. No. 22,775; Peter D. Olexy, Reg. No. 24,513; J. Frank Osha, Reg. No. 24,625; Waddell A. Biggart, Reg. No. 24,861; Robert G. McMorrow, Reg. No. 19,093; Louis Gubinsky, Reg. No. 24,835; Neil B. Siegel, Reg. No. 25,200; David J. Cushing, Reg. No. 28,703; John R. Inge, Reg. No. 26,916; Joseph J. Ruch, Jr., Reg. No. 26,577; Sheldon I. Landsman, Reg. No. 25,430; Richard C. Turner, Reg. No. 29,710; Howard L. Bernstein, Reg. No. 25,665; Alan J. Kasper, Reg. No. 25,426; Kenneth J. Burchfiel, Reg. No. 31,333; Gordon Kit, Reg. No. 30,764; Susan J. Mack, Reg. No. 30,951; Frank L. Bernstein, Reg. No. 31,484; Mark Boland, Reg. No. 32,197; William H. Mandir, Reg. No. 32,156; Scott M. Daniels, Reg. No. 32,562; Brian W. Hannon, Reg. No. 32,778 and Abraham J. Rosner, Reg. No. 33,276, my attorneys to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith, and request that all correspondence about the application be addressed to **SUGHRUE, MION, ZINN, MACPEAK & SEAS**, 2100 Pennsylvania Avenue, N.W., Washington, D.C. 20037-3202.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing therefrom.

Date	November 5, 1998	First Inventor	Takayasu	KOMATSU
Residence	Same as post office address	Signature	<u>Takayasu</u>	<u>Komatsu</u>
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Date	November 5, 1998	Second Inventor	Daisuke	HASHIMOTO
Residence	Same as post office address	Signature	<u>Daisuke</u>	<u>Hashimoto</u>
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Date: November 5, 1998 Third Inventor: Akira MAKITA
FIRST NAME MIDDLE INITIAL LAST NAME
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Date: November 5, 1998 Fourth Inventor: Koji FUJIYAMA
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Date: _____ Fifth Inventor: _____
FIRST NAME MIDDLE INITIAL LAST NAME
Residence: _____ Signature: _____
_____ Post Office Address: _____
Citizenship: _____

Date: _____ Sixth Inventor: _____
FIRST NAME MIDDLE INITIAL LAST NAME
Residence: _____ Signature: _____
_____ Post Office Address: _____
Citizenship: _____

Date: _____ Seventh Inventor: _____
FIRST NAME MIDDLE INITIAL LAST NAME
Residence: _____ Signature: _____
_____ Post Office Address: _____
Citizenship: _____

Date: _____ Eighth Inventor: _____
FIRST NAME MIDDLE NAME LAST NAME
Residence: _____ Signature: _____
_____ Post Office Address: _____
Citizenship: _____

(Supply similar information for ninth and subsequent joint inventors.)